

PROTECTION PRODUCTS - Z-Pak™

Description

μ Clamp[®] TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace 0201 size multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. They feature large cross-sectional area junctions for conducting high transient currents. These devices offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

μ Clamp[®]3311Z is constructed using Semtech's proprietary EPD process technology. The EPD process provides low standoff voltages with significant reductions in leakage currents and capacitance over silicon-avalanche diode processes. They feature a true operating voltage of 3.3 volts for superior protection when compared to traditional pn junction devices.

μ Clamp3311Z is in a 2-pin SLP0603P2X3A package. It measures 0.6 x 0.3 mm with a nominal height of only 0.25mm. Leads are finished with lead-free NiAu. Each device will protect one line operating at 3.3 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and MP3 players.

Features

- ◆ High ESD withstand Voltage: **+/-14kV** (Contact) and **+/- 16kV** (Air) per **IEC 61000-4-2**
- ◆ Able to withstand over 1000 ESD strikes per IEC 61000-4-2 Level 4
- ◆ Ultra-small **0201 package**
- ◆ Protects one data line
- ◆ Low reverse current: <10nA typical (VR=5V)
- ◆ Working voltage: +/- 3.3V
- ◆ Low capacitance: 6pF typical
- ◆ Extremely low dynamic resistance: 0.21 Ohms (Typ)
- ◆ Solid-state silicon-avalanche technology

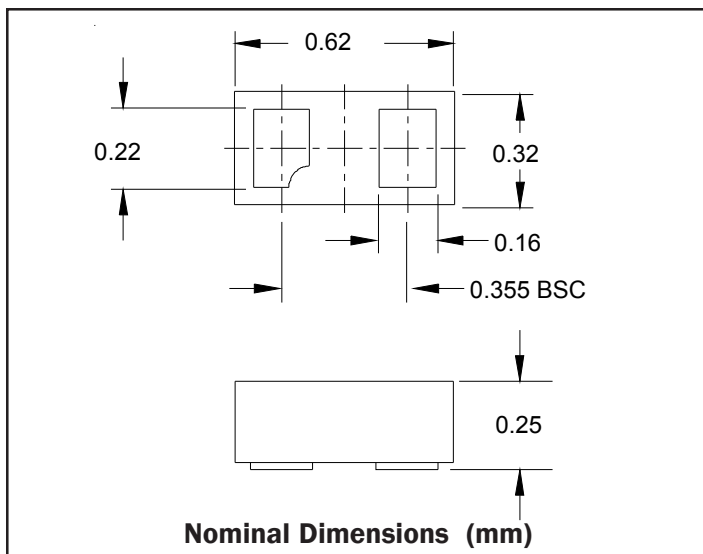
Mechanical Characteristics

- ◆ SLP0603P2X3A package
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant
- ◆ Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- ◆ Lead Finish: NiAu
- ◆ Marking : Marking code
- ◆ Packaging : Tape and Reel

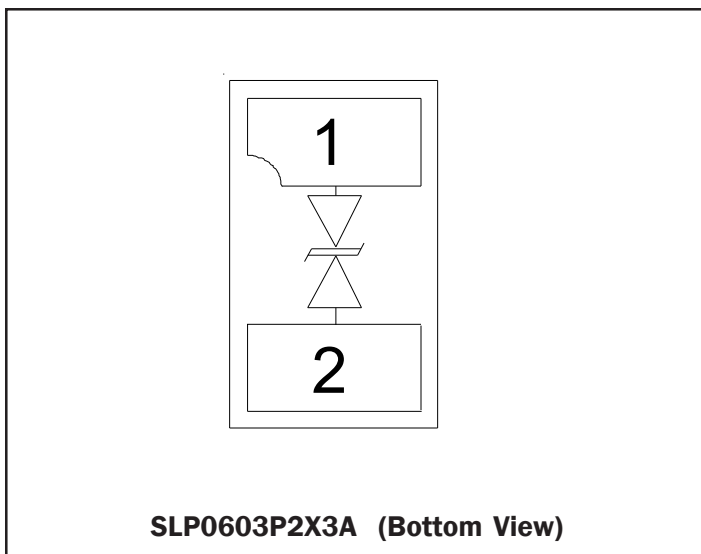
Applications

- ◆ Cellular Handsets & Accessories
- ◆ Keypads, Side Keys, Audio Ports
- ◆ Portable Instrumentation
- ◆ Digital Lines
- ◆ Tablet PC

Nominal Dimensions



Schematic



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Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{pk}	30	Watts
Maximum Peak Pulse Current ($t_p = 8/20\mu s$)	I_{pp}	4	Amps
ESD per IEC 61000-4-2 (Air) ¹ ESD per IEC 61000-4-2 (Contact) ¹	V_{ESD}	+/- 16 +/- 14	kV
Operating Temperature	T_J	-40 to +85	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Punch-Through Voltage	V_{PT}	$I_{PT} = 50\mu A$	3.65	4	4.4	V
Snap-Back Voltage	V_{SB}	$I_{SB} = 50mA$	2.8			V
Reverse Leakage Current	I_R	$V_{RWM} = 3.3V$		0.001	0.05	μA
Clamping Voltage	V_C	$I_{PP} = 1A, t_p = 8/20\mu s$			5.5	V
Clamping Voltage	V_C	$I_{PP} = 3A, t_p = 8/20\mu s$			6.5	V
Clamping Voltage	V_C	$I_{PP} = 4A, t_p = 8/20\mu s$			7.5	V
Dynamic Resistance ^{2, 3}	R_D	$t_p = 100ns$		0.21		Ohms
Junction Capacitance	C_j	I/O pin to Gnd $V_R = 0V, f = 1MHz$		6	9	pF

Notes

1)ESD gun return path connected to ESD ground reference plane.

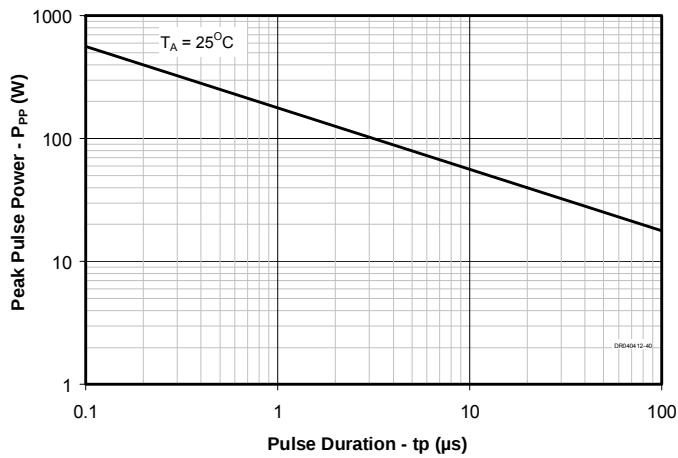
2)Transmission Line Pulse Test (TLP) Settings: $t_p = 100ns$, $t_r = 0.2ns$, I_{TLP} and V_{TLP} averaging window: $t_1 = 70ns$ to $t_2 = 90ns$.

3) Dynamic resistance calculated from $I_{TLP} = 4A$ to $I_{TLP} = 16A$

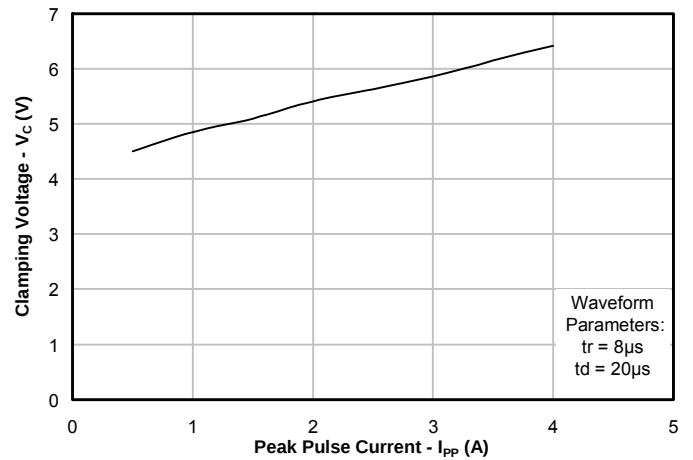
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Typical Characteristics

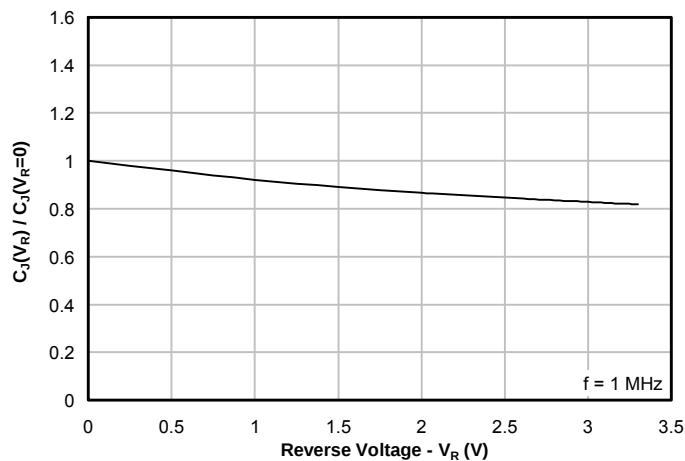
Non-Repetitive Peak Pulse Power vs. Pulse Time



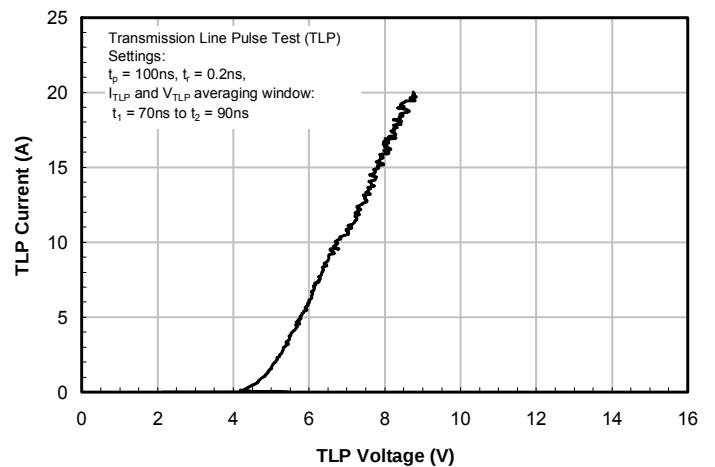
Clamping Voltage vs. Peak Pulse Current ($t_p=8/20\mu$ s)



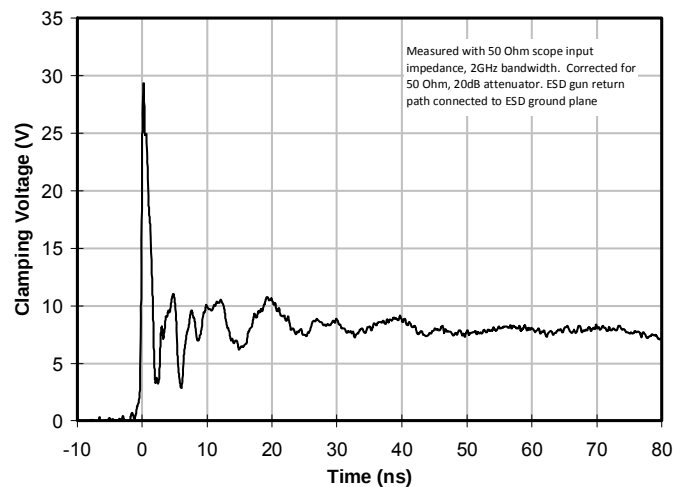
Normalized Junction Capacitance vs. Reverse Voltage



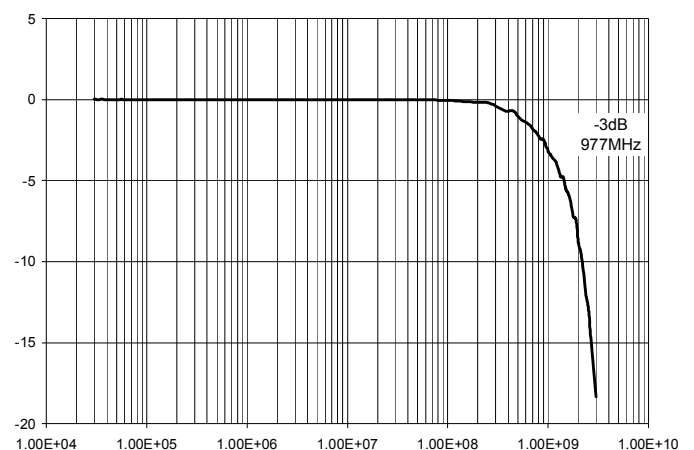
TLP Characteristic



ESD Clamping (+8kV Contact per IEC 61000-4-2)



**Typical Insertion Loss (S21)
30KHz to 3GHz**



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Applications Information

Device Connection Options

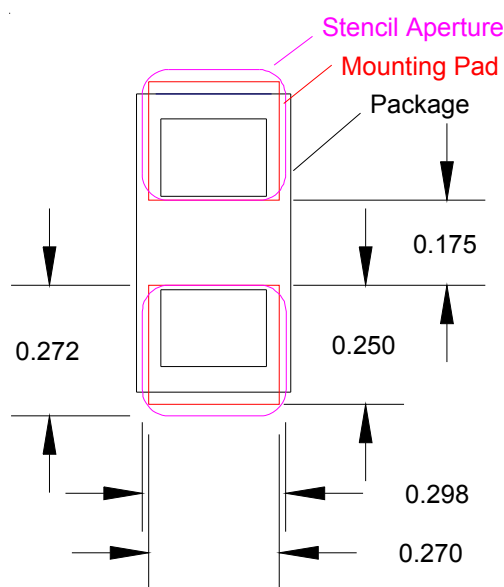
The μ Clamp3311Z is designed to protect one data line operating up to 3.3 volts. It will present a high impedance to the protected line up to 3.3 volts. It will “turn on” when the line voltage exceeds 3.5 volts. The device is bidirectional and may be used on lines where the signal polarity is above and below ground. These devices are not recommended for use on DC power supply lines due to their snap-back voltage characteristic.

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	Recommendation
Solder Stencil Design	Laser cut, Electro-polished
Aperture shape	Rectangular with rounded corners
Solder Stencil Thickness	0.100 mm (0.004")
Solder Paste Type	Type 4 size sphere or smaller
Solder Reflow Profile	Per JEDEC J-STD-020
PCB Solder Pad Design	Non-Solder mask defined
PCB Pad Finish	OSP OR NiAu

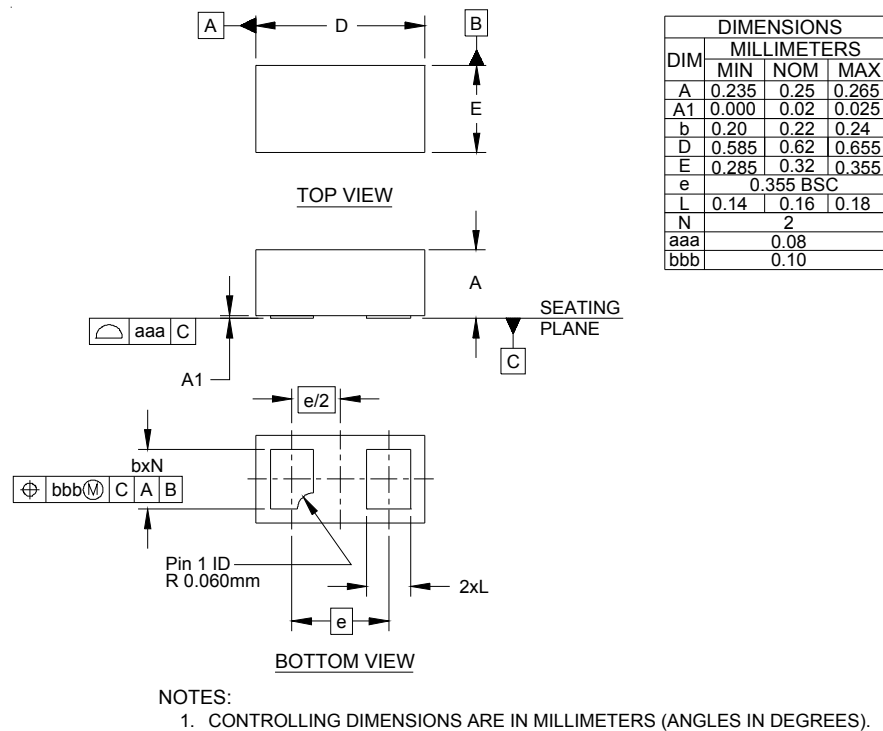
Circuit Diagram



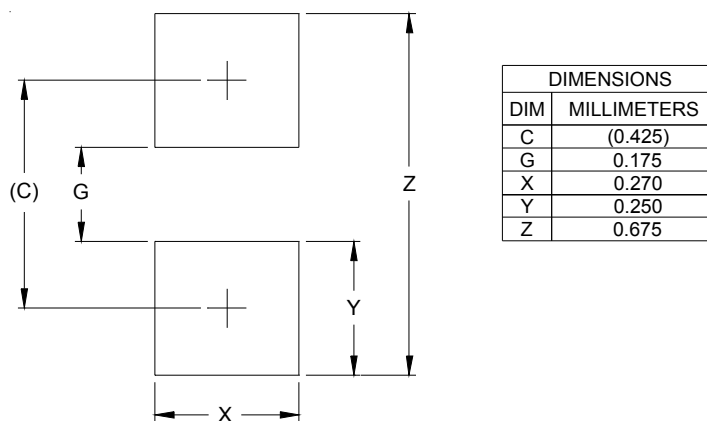
Recommended Mounting Pattern

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Outline Drawing - SLP0603P2X3A



Land Pattern - SLP0603P2X3A



- NOTES:**
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

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Marking Code



Notes:

1) Dots represent date code matrix and Pin 1 location

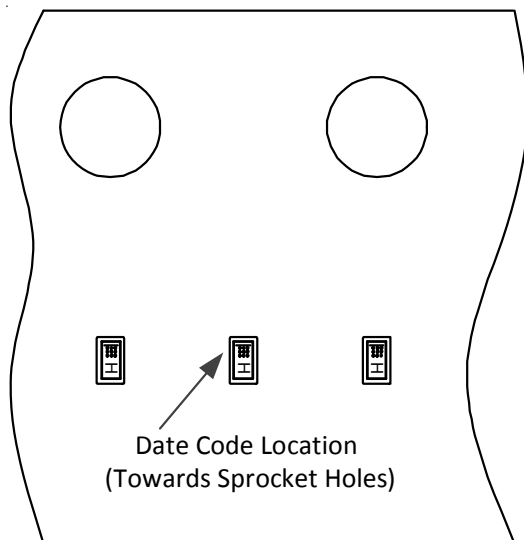
Ordering Information

Ordering Number	Qty per Reel	Carrier Tape	Reel Size	Comments
uClamp3311Z.TNT	10,000	Plastic	7 Inch	Not Recommended for New Designs
uClamp3311Z.TFT	15,000	Paper	7 Inch	
uClamp3311Z.TVT	50,000	Paper	13 Inch	

Notes:

1) MicroClamp, uClamp and μ Clamp are trademarks of Semtech Corporation

Device Orientation in Tape



Carrier Tape Specification

Technical drawing of a rectangular plate with dimensions and tolerances. The drawing includes a side view on the left and a top view on the right.

Side View Dimensions:

- Top flange thickness: 0.20 ± 0.02
- Plate thickness: Bo
- Bottom flange thickness: Ko

Top View Dimensions:

- Overall width: 4.00 ± 0.10
- Distance from left edge to first hole center: 2.00 ± 0.05
- Distance between hole centers: 2.00 ± 0.05
- Distance from last hole center to right edge: 2.00 ± 0.05
- Overall height: $8.00^{+0.30}_{-0.10}$
- Distance from top edge to hole center line: 1.75 ± 0.10
- Distance from hole center line to bottom edge: 3.50 ± 0.05
- Hole diameter: $\phi 1.50 \pm 0.10$
- Bottom flange thickness: 0.20 ± 0.05

Labels:

- Bo : Plate thickness
- Ko : Bottom flange thickness
- Ao : Distance from left edge to first hole center

Technical drawing of a mechanical part, showing a side view and a cross-section A-A.

Side View Dimensions:

- Hole diameter: $\phi 1.50^{+0.10}_{-0.00}$
- Distance between hole centers: 2.00 ± 0.05
- Distance from hole center to right edge: 4.00 ± 0.10
- Distance from hole center to left edge: 0.42 ± 0.03
- Distance between square hole centers: 2.00 ± 0.05
- Distance from square hole center to right edge: 0.39 ± 0.03
- Distance from square hole center to left edge: 0.29 ± 0.02
- Overall width: 8.00 ± 0.10
- Distance from top edge to hole center: 1.75 ± 0.05
- Distance from bottom edge to hole center: 3.50 ± 0.05

Cross-section A-A Dimensions:

- Top flange thickness: 0.42 ± 0.03
- Web thickness: 0.69 ± 0.03
- Bottom flange thickness: 0.29 ± 0.02

Section Labels:

- SECTION A-A
- Bo
- Ko
- AO

Note: All dimensions in mm unless otherwise specified

Contact Information

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